# MSKSEMI 美森科













**ESD** 

TV

TSS

MOV

GDT

PLED

## **MURSXXXB-MS**

**Product specification** 





#### SURFACE MOUNT ULTRAFAST RECTIFIER

**VOLTAGE:300V TO 600V** 

**CURRENT: 3.0A** 

## **Features**

- Ideally suited for use in very high frequency switching power
- supplies, inverters and as free wheeling diodes
- Ultrafast recovery time for high efficiency
- High surge capability
- High temperature soldering guaranteed
- 260°C/10sec/at terminals
- Glass passivated chip

## **Mechanical Data**

- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Case: Molded with UL-94 class V-0 recognized Flame Retardant Epoxy
- Polarity: Color band denotes cathode end

## **Reference News**

PACKAGE OUTLINE	Marking
	MURS ***
SMB(DO-214AA)	*** Representative VRRM



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (single-phase, half-wave, 60HZ, resistive or

inductive load rating at 25°C, unless otherwise stated,for capacitive load, derate current by 20%)

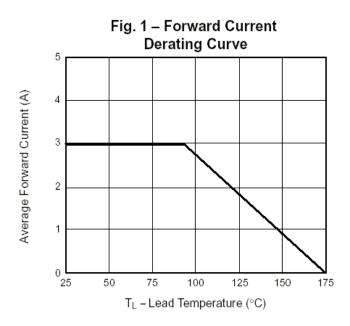
	SYMBOL	MURS330B-MS	MURS340B-MS	MURS360B-MS	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	300	400	600	V
Maximum RMS Voltage	Vrms	210	280	420	V
Maximum DC blocking Voltage	Vdc	300	400	600	V
Maximum Average Forward Rectified Current 3/8″lead length at T <sub>L</sub> =90 °C	If(av)	3.0			А
Peak Forward Surge Current 8.3ms single half sine- wave superimposed on rated load	Ifsm	125.0		А	
Maximum Instantaneous Forward Voltage at rated forward current $T_J$ =25 $^{\circ}$ C	Vf	1.25		V	
Maximum DC Reverse Ta=25℃ Current at rated DC blocking voltage Ta =125℃	lr	10.0 50.0		μA	
Maximum Reverse Recovery Time (Note1)	Trr	50		nS	
Typical Junction Capacitance (Note 2)	Cj	50		pF	
Typical Thermal Resistance, junction to lead	Rth(jl)	11		°C/W	
Storage and Operating Junction Temperature	Tstg, Tj	-55 to +175		$^{\circ}$	

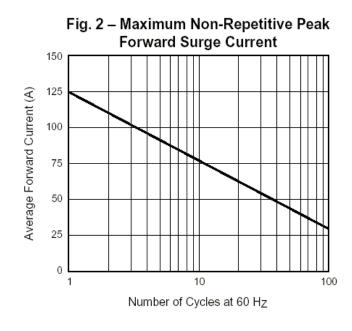
#### Note:

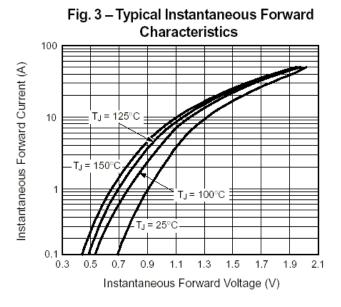
- 1. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
- 2. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc

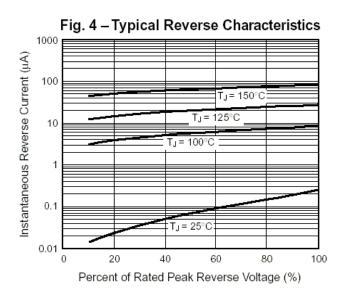


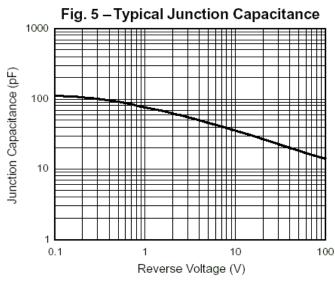
#### RATINGSANDCHARACTERISTICCURVES MURSXXXB-MS





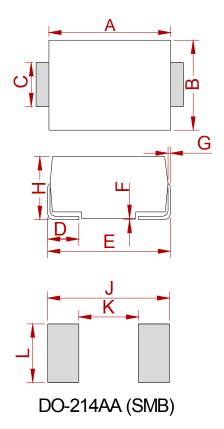








## **PACKAGE MECHANICAL DATA**



	Dimensions			
Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
Α	4.25	4.75	0.167	0.187
В	3.30	3.94	0.130	0.155
С	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
Е	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
Н	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

## **REEL SPECIFICATION**

P/N	PKG	QTY
MURSXXXB-MS	DO-214AA(SMB)	3000



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